
INITIAL PRODUCT/PROCESS CHANGE NOTIFICATION #20767

Generic Copy

Issue Date: 03-Feb-2015

TITLE: Release dual fab sourcing for NCV7462DQ0R2G, NCV7471DQ5R2G and NCV7381DP0R2G - I3T80 technology; currently manufactured in Fab2 Belgium; add manufacturing in Gresham USA.

PROPOSED FIRST SHIP DATE: 03-Feb-2016 or earlier upon customer approval

AFFECTED CHANGE CATEGORY(S): Wafer Fab Manufacturing

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:
Contact your local ON Semiconductor Sales Office or your Customer Quality interface

NOTIFICATION TYPE:
Initial Product/Process Change Notification (IPCN)

First change notification sent to customers. IPCNs are issued at least 120 days prior to implementation of the change. An IPCN is advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN).

This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. The target date for FPCN submission is Q4 2015.

DESCRIPTION AND PURPOSE:
Release Gresham as an additional wafer fab location for NCV7462DQ0R2G, NCV7471DQ5R2G, NCV7381DP0R2G, in order to increase ON Semiconductor's wafer fab capacity for these devices.

QUALIFICATION PLAN:
Refer to the attached qualification plans

Estimated Date for Qualification Completion: 01-Oct-2015
Samples should be available after completion of Qualification.

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List of Affected General Parts:

NCV7462DQ0R2G
NCV7471DQ5R2G
NCV7381DP0R2G